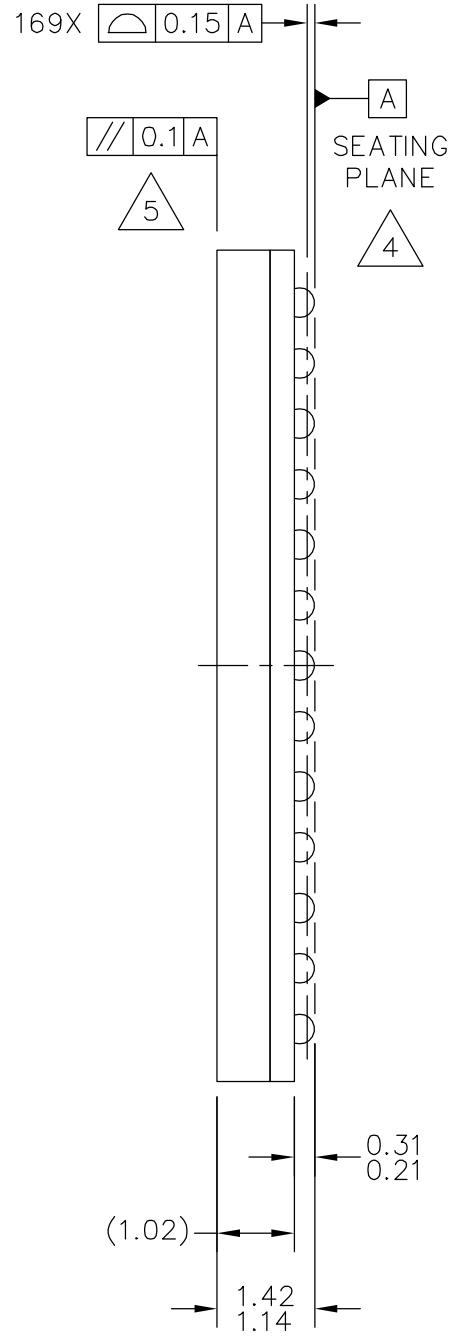
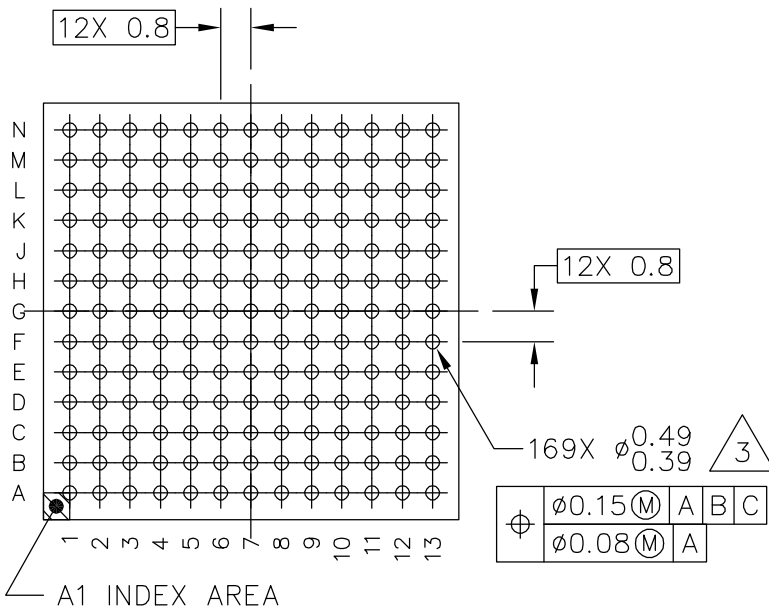


TOP VIEW



SIDE VIEW



BOTTOM VIEW

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TITLE: PBGA, LOW PROFILE, FINE PITCH, 169 I/O, 11 X 11 PKG, 0.8 MM PITCH (MAP)	DOCUMENT NO: 98ARE10745D	REV: B
	STANDARD: NON-JEDEC	
	SOT1542-1	03 FEB 2016



NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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